



# SOT1167-1

DFN2514-12: plastic, thermal enhanced ultra thin small outline package; no leads; 12 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN2514-12
<b>Package type industry code</b>	DFN2514-12
<b>Package style descriptive code</b>	HUSON (thermal enhanced ultra thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-3-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	[tbd]	-	[tbd]	0.55	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	12	-	



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## 2. Package outline

HUSON12: plastic, thermal enhanced ultra thin small outline package; no leads; 12 terminals; body 1.35 x 2.5 x 0.55 mm

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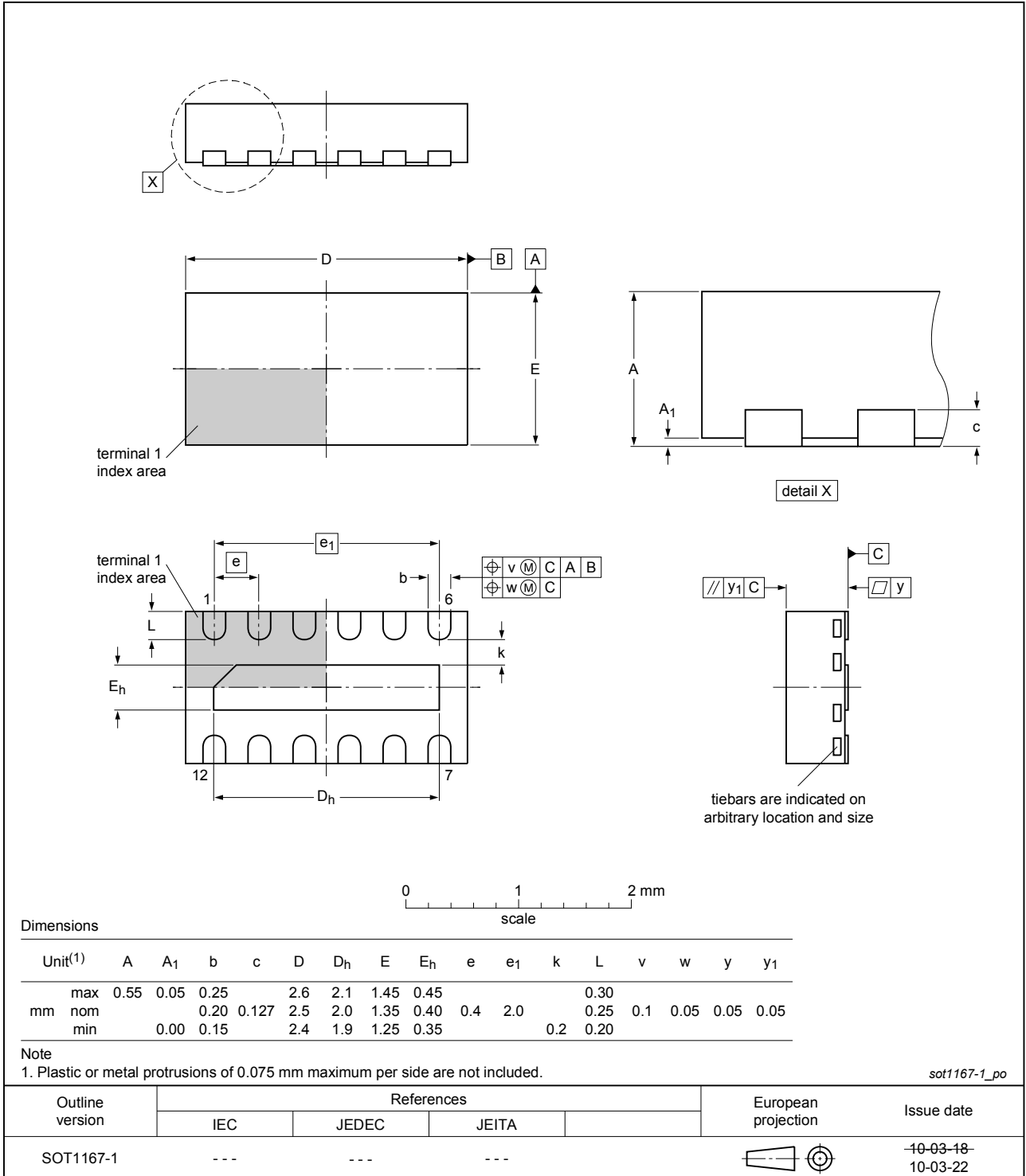


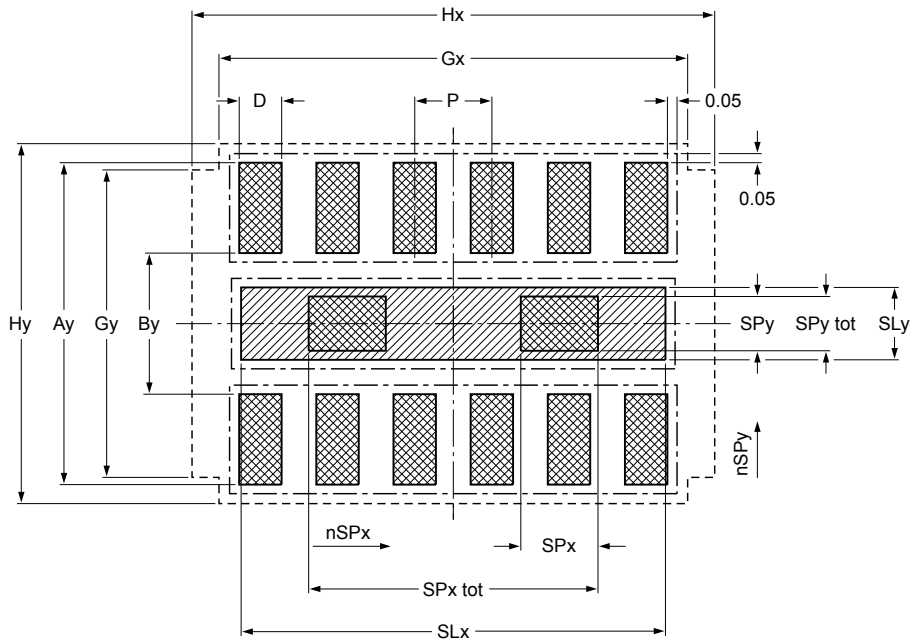
Fig. 1. Package outline DFN2514-12 (SOT1167-1)

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### 3. Soldering

Footprint information for reflow soldering of HUSON12 package

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Generic footprint pattern

Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- - - - solder resist

DIMENSIONS in mm

P	Ay	By	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy	nSPx	nSPy
0.400	1.780	0.780	0.220	2.200	0.400	1.500	0.300	0.400	0.300	2.430	1.700	2.710	1.990	2	1

Issue date 12-08-15  
12-08-27

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Fig. 2. Reflow soldering footprint for DFN2514-12 (SOT1167-1)

## 4. Legal information

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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